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## SEHO Receives Award for Integrating Additional Processes in Its Selective Soldering Systems

SEHO Systems GmbH is pleased to announce that it was awarded a 2017 Global Technology Award in the category of Soldering – Selective for its Integrated Additional Processes in Selective Soldering Systems. The award was presented to the company during a Tuesday, Nov. 14, 2017 ceremony that took place during productronica in Munich, Germany. The SEHO PowerSelective and SEHO SelectLine selective soldering systems can be equipped with an automated selective brush system and an AOI system for immediate automatic cleaning and inspection of solder joints directly after the soldering process. All processes are integrated in ONE machine.



The ability to reduce production costs while maintaining consistently high quality is essential for electronic production. Solder balls represent a soldering defect that is considered particularly critical. There are numerous reasons for the formation of solder balls in selective soldering processes, ranging from poor process setup, up to the material used, such as the solder resist of the PCB. Solder balls can cause shorts leading to complete failure of the assembled product. Other typical soldering defects such as solder bridges, insufficient wetting or open solder joints also can severely affect the product quality and reliability. Considering that manual cleaning or repair processes after soldering are not only expensive and time-consuming but also provide poor reproducibility, the target, therefore, is an automated and fully controlled zero-fault process.

With SEHO's Integrated Additional Processes in Selective Soldering Systems, all processes – selective fluxing, preheating, soldering with selective mini-wave, multi-nozzle or even conventional wave soldering, selective brushing, AOI and cooling – can be performed in parallel for different boards. Therefore, the additional processes do not influence the cycle time. The advantages of the additional functions are obvious:



Safe and reliable processes on the one hand, and reduced overall production costs on the other hand, as the integrated additional processes use the handling units of the soldering machines (conveyors, axes, grippers etc.) and in addition they do not require extra floor space.

Premiering in 2005, the Global Technology Awards program is an annual celebration of product excellence in electronics surface mount assembly. Premier products based on the finest examples of creative advancement in technology are chosen by a distinguished panel of industry experts.